



General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

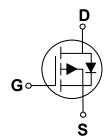
BV _{DSS}	R _{DS(ON)}	I _D
-100 V	95 mΩ	-30 A

Features

- $R_{DS(ON)} \leq 95m\Omega @V_{GS} = -10V$
- · Fast Switching
- · Green Device Available
- · Improved dv/dt Capability

TO-252 Pin Configuration





Applications

- · Brushless Motor
- · Uninterruptible Power Supply
- · Load Switch

Absolute Maximum Ratings T _c =25°C unless otherwise noted						
Symbol	Symbol Parameter		Units			
V _{DS}	Drain-Source Voltage	-100	V			
V_{GS}	Gate-Source Voltage	±20	V			
I _D	Drain Current - Continuous (T _C =25°C)	-30	Α			
I _{DM}	Drain Current - Pulsed (NOTE 1)	-90	Α			
EAS	Single Pulse Avalanche Energy (NOTE 2)	18	mJ			
IAS	Single Pulse Avalanche Current (NOTE 2)	-19	Α			
P _D	Power Dissipation (T _C =25°C)	54.3	W			
T_J	Operating Junction Temperature Range	-55 to 150	°C			
T _{STG}	Storage Temperature Range	-55 to 150	°C			
Marking Code		PM095				

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	62.5	°C/W		
$R_{ heta JC}$	Thermal Resistance Junction to Case	2.3	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V , I _D = -250uA	-100			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} = -100V , V _{GS} = 0V			-50	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = ±20V , V_{DS} = 0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V_{GS} = -10V , I_D = -10A			95	- mΩ
		V_{GS} = -4.5V , I_D = -8A			110	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250uA$	-1.2		-2.5	V
gfs	Forward Transconductance	V_{DS} = -10V , I_D = -10A		24		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V _{DS} = -50V , V _{GS} = -10V ,		44.5		
Q_gs	Gate-Source Charge	$I_{D} = -20A$		9.13		nC
Q_{gd}	Gate-Drain Charge	10 2071		5.93		
T _{d(on)}	Turn-On Delay Time			12		
T_r	Rise Time	V_{DD} = -50V , V_{GS} = -10V , R_{G} = 3.3 Ω , I_{D} = -10A		27.4		nS
$T_{d(off)}$	Turn-Off Delay Time			79		113
T_f	Fall Time			53.6		
C _{iss}	Input Capacitance			3029		
C _{oss}	Output Capacitance	V_{DS} = -20V , V_{GS} = 0V , F= 1MHz		129		pF
C_{rss}	Reverse Transfer Capacitance			76		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	$V_G = V_D = 0V$, Force Current			-30	Α
V_{SD}	Diode Forward Voltage	V _{GS} = 0V , I _S = -1A	-		-1.2	V
t _{rr}	Reverse Recovery Time	I _F = -8A , di/dt=-100A/us	-	38.7		nS
Q_{rr}	Reverse Recovery Charge			22.4		nC

NOTES:

- 1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =-72V, V_{GS} =-10V, L=0.1mH, I_{AS} =-19A.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.





Characteristics Curves

FIG. 1-Output Characteristics

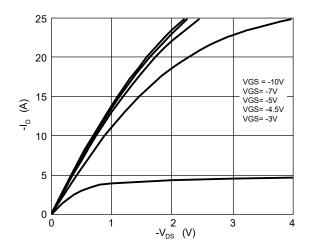


FIG. 2-R_{DS(ON)} vs V_{GS}

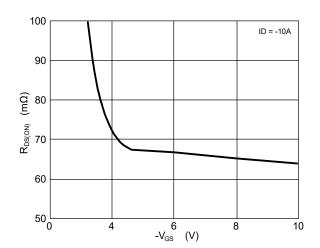


FIG. 3-I $_{\rm S}$ vs V $_{\rm SD}$

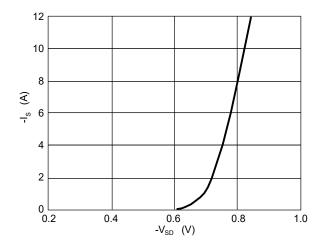


FIG. 4-Gate Charge Characteristics

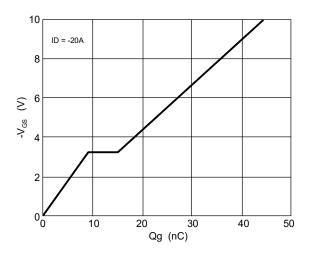


FIG. 5-Normalized $V_{GS(th)}$ vs T_J

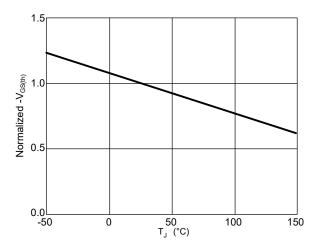
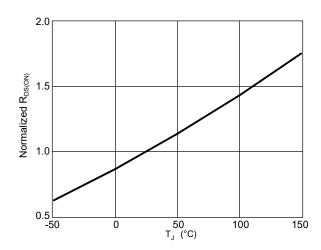


FIG. 6-Normalized R_{DS(ON)} vs T_J







Characteristics Curves

FIG. 7-Switching Time Waveform

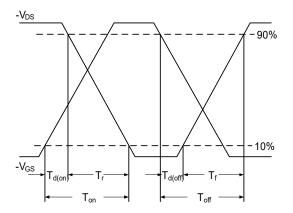
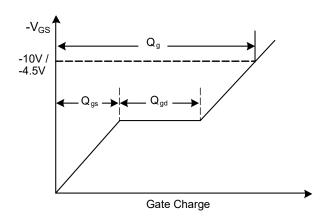
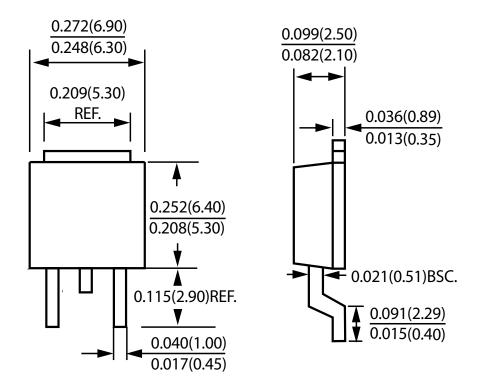


FIG. 8-Gate Charge Waveform



Package Outline Dimensions



TO-252
Dimensions in inches and (millimeters)





LEGAL DISCLAIMER

- The product is provided "AS IS" without any guarantees or warranty. In association with the product, Eris Technology Corporation, its affiliates, and their directors, officers, employees, agents, successors and assigns (collectively, the "Eris") makes no warranties of any kind, either express or implied, including but not limited to warranties of merchantability, fitness for a particular purpose, of title, or of non-infringement of third party rights.
- The information in this document and any product described herein are subject to change without notice and should not be construed as a commitment by Eris. Eris assumes no responsibility for any errors that may appear in this document.
- Eris does not assume any liability arising out of the application or use of this document or any product described herein, any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Eris and all the companies whose products are represented on Eris website, harmless against all damages.
- No license, express or implied, by estoppels or otherwise, to any intellectual property is granted by this document or by any conduct of Eris. Product name and markings notes herein may be trademarks of their respective owners.
- Eris does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
- Should Customers purchase or use Eris products for any unintended or unauthorized application, Customers shall indemnify and hold Eris and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.
- The official text is written in English and the English version of this document is the only version endorsed by Eris. Any discrepancies or differences created in the translations are not binding and have no legal effect on Eris for compliance or enforcement purposes.